Single 2-Input Exclusive OR Gate, TTL Level

LSTTL-Compatible Inputs

The NLU1GT86 MiniGate[™] is an advanced CMOS high-speed 2-input Exclusive OR gate in ultra-small footprint.

The device input is compatible with TTL-type input thresholds and the output has a full 5.0 V CMOS level output swing.

The NLU1GT86 input and output structures provide protection when voltages up to 7.0 V are applied, regardless of the supply voltage.

Features

- High Speed: $t_{PD} = 3.1 \text{ ns (Typ)} @ V_{CC} = 5.0 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu A$ (Max) at $T_A = 25^{\circ}C$
- TTL-Compatible Input: $V_{IL} = 0.8 \text{ V}$; $V_{IH} = 2.0 \text{ V}$
- CMOS–Compatible Output:

 V_{OH} > 0.8 $V_{CC};\,V_{OL}$ < 0.1 V_{CC} @ Load

- Power Down Protection Provided on inputs
- Balanced Propagation Delays
- Ultra-Small Packages
- These are Pb-Free Devices

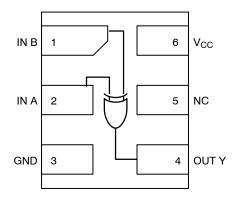


Figure 1. Pinout (Top View)

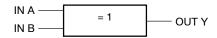


Figure 2. Logic Symbol

FUNCTION TABLE

Inp	Output	
Α	В	Y
_	⊔	L H H L

PIN ASSIGNMENT

1	IN B
2	IN A
3	GND
4	OUT Y
5	NC
6	V _{CC}



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MARKING DIAGRAMS



UDFN6 1.2 x 1.0 CASE 517AA



6 = Device Marking M = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V
V _{IN}	DC Input Voltage	-0.5 to +7.0	V
V _{OUT}	DC Output Voltage	-0.5 to +7.0	V
I _{IK}	DC Input Diode Current V _{IN} < GND	-20	mA
lok	DC Output Diode Current V _{OUT} < GND	±20	mA
I _O	DC Output Source/Sink Current	±12.5	mA
Icc	DC Supply Current Per Supply Pin	±25	mA
I _{GND}	DC Ground Current per Ground Pin	±25	mA
T _{STG}	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	150	°C
MSL	Moisture Sensitivity	Level 1	
F _R	Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 150 N/A	V
I _{LATCHUP}	Latchup Performance Above V _{CC} and Below GND at 125°C (Note 5)	±500	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

- 2. Tested to EIA / JESD22-A114-A.
- 3. Tested to EIA / JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA / JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.65	5.5	V
V _{IN}	Digital Input Voltage	0	5.5	V
V _{OUT}	Output Voltage	0	5.5	V
T _A	Operating Free-Air Temperature	-55	+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate $ V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V} $	0 0	100 20	ns/V

DC ELECTRICAL CHARACTERISTICS

				т	_ A = 25 °	С	T _A = -	⊦85°C	T _A = - to +1	-55°C 25°C	
Symbol	Parameter	Conditions	V _{CC} (V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Low-Level Input Voltage		3.0 4.5 to 5.5	1.4 2.0			1.4 2.0		1.4 2.0		V
V _{IL}	Low-Level Input Voltage		3.0 4.5 to 5.5			0.53 0.8		0.53 0.8		0.53 0.8	V
V _{OH}	High-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -50 \mu A$	3.0 4.5	2.9 4.4	3.0 4.5		2.9 4.4		2.9 4.4		V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -4 \text{ mA}$ $I_{OH} = -8 \text{ mA}$	3.0 4.5	2.58 3.94			2.48 3.80		2.34 3.66		
V _{OL}	Low-Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 50 \mu A$	3.0 4.5		0.0 0.0	0.1 0.1		0.1 0.1		0.1 0.1	V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 4 \text{ mA}$ $I_{OL} = 8 \text{ mA}$	3.0 4.5			0.36 0.36		0.44 0.44		0.52 0.52	
I _{IN}	Input Leakage Current	$0 \le V_{IN} \le 5.5 V$	0 to 5.5			±0.1		±1.0		±1.0	μΑ
I _{CC}	Quiescent Supply Current	$0 \le V_{IN} \le V_{CC}$	5.5			1.0		20		40	μΑ
I _{CCT}	Quiescent Supply Current	V _{IN} = 3.4 V	5.5			1.35		1.50		1.65	mA
I _{OPD}	Output Leakage Current	V _{OUT} = 5.5 V	0.0			0.5		5.0		10	μΑ

AC ELECTRICAL CHARACTERISTICS (Input t_{r} = t_{f} = 3.0 ns)

		V _{CC}	Test	т	' _A = 25 °(С	T _A = +	-85°C	T _A = - to +1	-55°C 25°C	
Symbol	Parameter	(V)	Condition	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Propagation Delay, Input A to	3.0 to	C _L = 15 pF		5.0	11.0		13.0		15.5	ns
^L PHL	t _{PHL} Output Y	HL Output Y	Output Y	6.2	14.5		16.5		19.5		
		4.5 to	C _L = 15 pF		3.1	6.8		6.0		10.0	
		5.5	C _L = 50 pF		4.2	8.8		10.0		12.0	
C _{IN}	Input Capacitance				5.5	10		10		10.0	pF
C _{PD}	Power Dissipation Capacitance (Note 6)	5.0			11						pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the dynamic operating current consumption without load. Average operating current can be obtained by the equation I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption: P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.

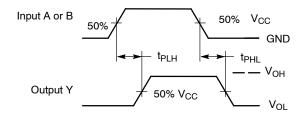
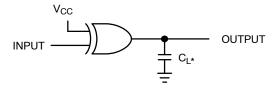


Figure 3. Switching Waveforms



*Includes all probe and jig capacitance.

A 1-MHz square input wave is recommended for propagation delay tests.

Figure 4. Test Circuit

ORDERING INFORMATION

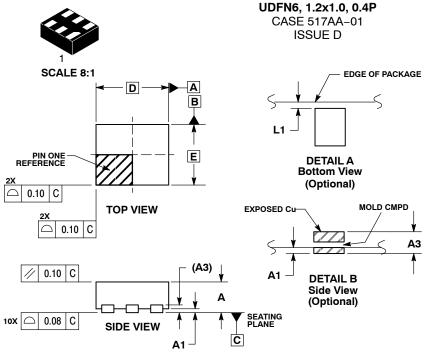
Device	Device Package			
NLU1GT86MUTCG	UDFN6, 1.2 x 1.0, 0.4P (Pb-Free)	3000 / Tape & Reel		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

6X b

0.10 C A B

0.05 C NOTE 3



- 5X L

е

BOTTOM VIEW

517AA-01 SSUE D

DATE 03 SEP 2010

NOTES

- DIMENSIONING AND TOLERANCING PER
 ASME Y14 5M 1994
- ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
- DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 mm FROM TERMINAL.
 COPLANARITY APPLIES TO THE EXPOSED
- 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS						
DIM	MIN MAX						
Α	0.45	0.55					
A1	0.00	0.05					
А3	0.127	REF					
b	0.15	0.25					
D	1.20	BSC					
Е	1.00	BSC					
е	0.40	BSC					
L	0.30	0.40					
L1	0.00	0.15					
12	0.40 0.50						

GENERIC MARKING DIAGRAM*

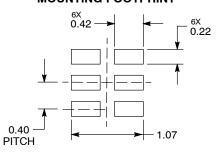


X = Specific Device CodeM = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •",

MOUNTING FOOTPRINT*

may or may not be present.



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON22068D	Electronic versions are uncontrolled except when accessed directly from the Document Repos Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.				
DESCRIPTION:	6 PIN UDFN, 1.2X1.0, 0.4P		PAGE 1 OF 1			

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